



Layer Stack Up Detail for: RTM_SFP.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.0102mm	Solder Resist	3.50	
Top Layer	(.GTL)	0.0356mm	0.36mm	FR-4	4.80	PrePreg
MidPlane_1	(.GP1)	0.0356mm	0.71mm	FR-4	4.80	Core
MidPlane_2	(.GP2)	0.0356mm	0.36mm	FR-4	4.80	PrePreg
Bottom Layer	(.GBL)	0.0356mm				
Bottom Solder Mask	(.GBS)		0.0102mm	Solder Resist	3.50	

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Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.0102mm	Solder Resist	3.50	
Top Layer	(.GTL)	0.0356mm	0.381mm	FR-4	4.80	PrePreg
PWR	(.GP1)	0.0356mm	0.71mm	FR-4	4.80	Core
GND	(.GP2)	0.0356mm	0.381mm	FR-4	4.80	PrePreg
Bottom Layer	(.GBL)	0.0356mm				
Bottom Solder Mask	(.GBS)		0.0102mm	Solder Resist	3.50	